

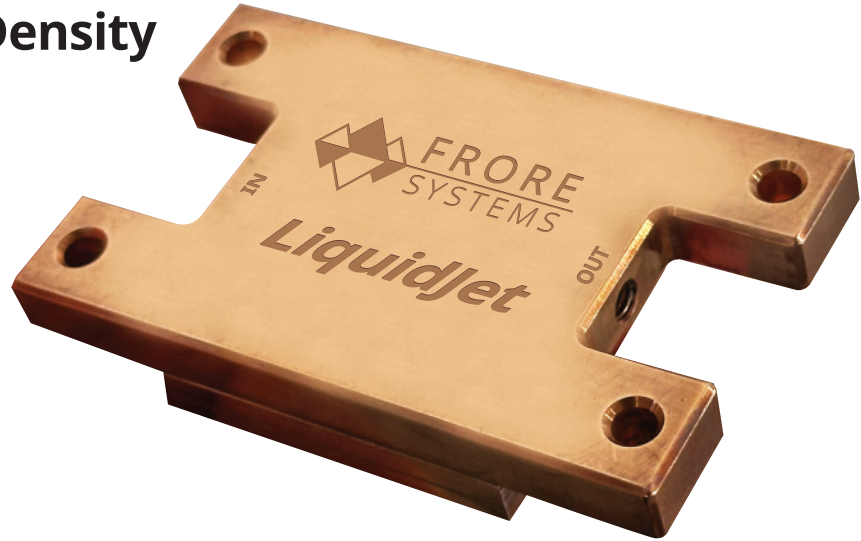
LiquidJet™ Coldplate



2x Higher Hotspot Power Density

50% More Heat Removal

4x Lower Pressure Drop



Our breakthrough design with innovative 3D short-loop jet channel microstructures - an industry first - enables:

- 2x higher hotspot power density of 600 W/cm^2 @40°C inlet temperature
- 50% higher KW/lpm
- 4x lower pressure drop
- Customized designs to exactly match any SOC power map
- Easy drop-in upgrade

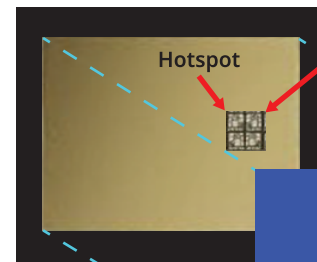
Performance on Blackwell Ultra*

	Best Skived Coldplate	LiquidJet Coldplate
SOC Power (W)	1400	1400
Microstructure Pressure Drop (psi)	0.94	0.24
PG25 Flow Rate (lpm)	2.1	1.4

Note: Max Channel Width 0.15mm | Inlet Flow Temp: 40C | TIM: PTM7950

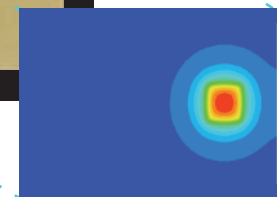
* Measured on a thermal test vehicle.

GPU with Hotspot



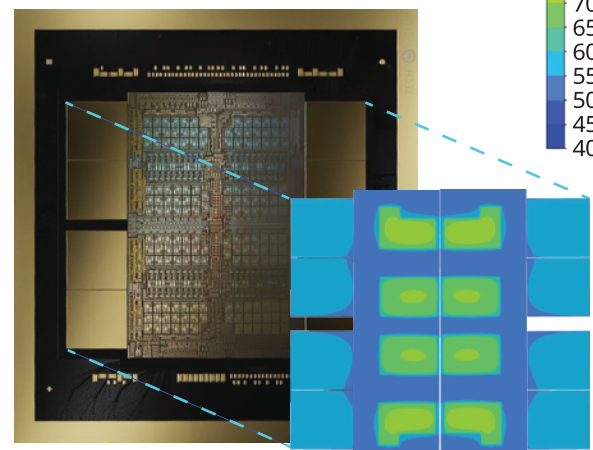
600 W/cm²

(with TIM: 0.02 K cm²/W
Rest of Die 80 W/cm²)



Die Temp (T_j) with LiquidJet

Blackwell Ultra



Die Temp (T_j) with LiquidJet

LiquidJet™ Coldplate

Customizable Cooling

Legacy coldplates rely on outdated skiving 2D microchannel manufacturing, limiting their ability to adapt to new chip layouts and increasingly non-uniform high power density requirements.

Frore Systems takes a different approach, adapting semiconductor manufacturing to metal wafers, fabricating 3D short-loop jet channel microstructures that are designed precisely to the power maps of modern GPUs.

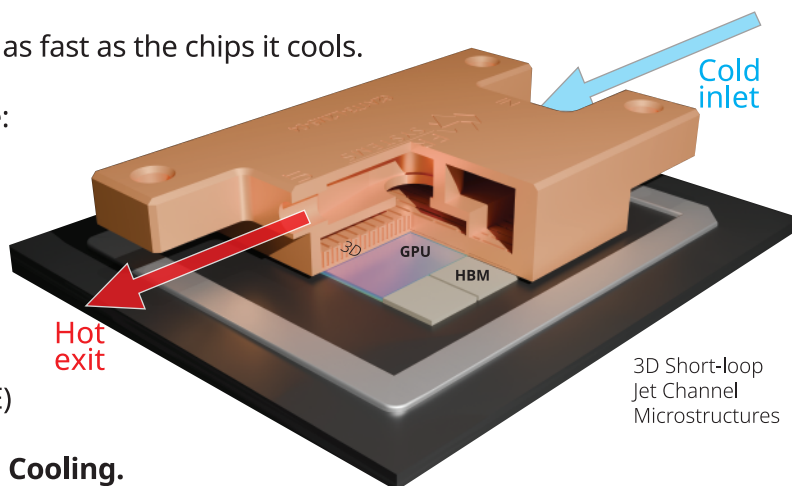
Customizable to match the exact power density of your SOC.

The result is LiquidJet, a coldplate that evolves as fast as the chips it cools.

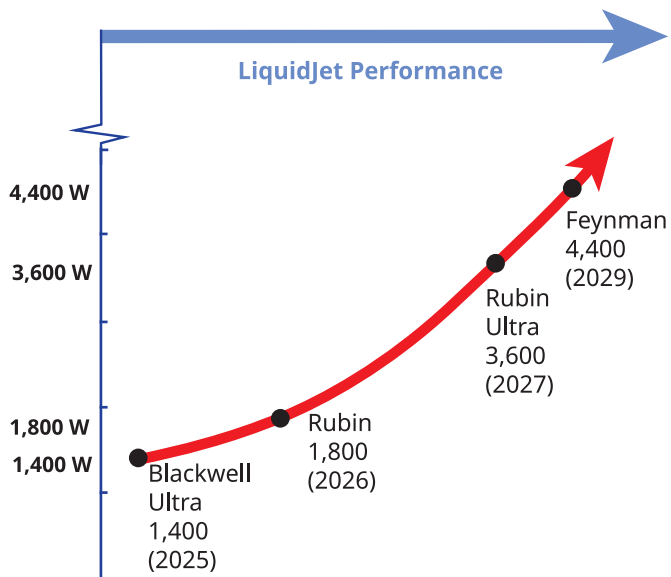
With these advances, data centers can achieve:

- Cooler GPUs
- More AI tokens/second
- Lower total cost of ownership (TCO)
- Improved power usage effectiveness (PUE)

LiquidJet - Redefining AI Data Center Liquid Cooling.



Future-proof supporting NVIDIA Feynman SoC & beyond



Frore Systems Copyright 2025. Specification subject to change. Patents Pending.



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